Electronic Supporting Information

Photoelectrochemical Hydrogen Generation employing a Cu₂O-based Photocathode with improved Stability and Activity by using Ni_xP_y as the cocatalyst.

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Materials and Chemicals: Copper sulfate pentahydrate [Sigma Aldrich, CuSO₄,5H₂O], Lactic acid [SD Fine Chem. India], Sodium Hydroxide [Sigma Aldrich, NaOH], FTO slide [Sigma Aldrich, surface resistivity ~7 ohm/cm²], Nickel Acetate [Sigma Aldrich, Ni(OAc)₂], Phosphoric acid [H₃PO₄ SD Fine Chem. India], Phosphorous acid [H₃PO₃ SD Fine Chem. India], N-methylformamide (NMF) [SD Fine Chem. India], Cu wires, Enamel remover, Ag paste.

Characterizations: Powder X-ray diffraction (PXRD) of photoanodes was recorded using a Bruker AXS D8 Discover diffractometer attached with Cu K α radiation. X-ray photoelectron spectroscopy (XPS, Mg–K α X ray source, 1253.6 eV) was recorded to analyze the surface composition of samples. UV–Vis absorption spectra were examined using a UV-Perkin Elmer UV/Vis spectrometer. Transmission electron microscopy (TEM, Technai F30 UHR, 200 kV) was used to study the crystal morphology and composition (HRTEM) and Field emission scanning electron microscopy (FESEM, FEI Quanta operated at 15 kV, equipped with EDAX) was used to investigate the composition, morphology and thickness of various layers in electrodes. The elemental ratios of the as prepared electrodes were confirmed by optical emission spectrometry-inductively coupled plasma spectrometry (OES–ICP) (Perkin Elmer Optima 7000 DV).

Sample Preparation for Characterizations: For XPS analysis the deposited electrode as kept in ambient atmosphere were directly used without any further processing. Mg–Kα X ray was used as non-monochromatic source with hemispherical electron energy analyzer.

Electrochemical Impedance Spectroscopy analysis: The data points were fitted by CHI760E inbuilt software (Model 700E Series Electrochemical Analyzer/Workstation, CHI Inc., with simulations and fitting commands) by proposing an equivalent modified Randles' circuit model described. An impedance simulator is integrated into the program. The fitting error is ~0.01 and elapsed time ~450 seconds. The symbols represent the experimental data and the lines represents fitting results utilizing the equivalent circuit.

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Element	Impedance	Conductance	Phase
R (resistor)	$Z_R = R$	$Y_R = 1/R$	Φ = 0
C (capacitor)	Z _c = -j/C	$Y_{c} = j\omega C$	Φ = π/2
Q (phase)	$Z_Q = (j\omega)^{-n}/Yo$	$Y_Q = (j\omega)^n Yo$	$\Phi = n\pi/2, \ 0 < n < 1$

Circuit Element Properties: R=Resistor; C=Capacitor; Q= Constant phase element; j=current density; ω = frequency

Reference- CHI Instruments Manual; J. R. Macdonald, Ann. Biomed. Eng., 20, 289-305 (1992) or "Impedance Spectroscopy", E. Barsoukov and J. R. Macdonald, Wiley, Hoboken, 1987 (1st ed), 2005 (2nd ed).

X-Ray Photoelectron Spectroscopy analysis: XPS analysis was done using XPSPEAK4.1 software. Background subtraction was performed using Shirley functions with the optimizations to bring the Shirley background data points which are higher than the signal intensities at some points. The optimization helps in increasing the slope value until the Shirley background is below the signal intensities. To add peaks for the deconvulation of XPS core level peak, Gaussian-Lorentzian sum function was used with adjustable parameters like peak position, peak area, FWHM and % Gaussian-Lorentzian functions. Depending on the number of anticipated peaks, the peak were deconvulated by adjusting the parameters until the final combined peak from various added peaks matched with the actual data obtained from XPS measurement (raw data).

XPS Discussion: In the X-Ray photoelectron spectroscopy (XPS) distinction between the Cu₂O and CuO phases could be made from the binding energies of the Cu $2p_{1/2}$ and $2p_{3/2}$. Core level XPS spectra of photocathode thin films are plotted in **Fig. 1b** with respective peak positions of the Cu $2p_{1/2}$ and $2p_{3/2}$ along with satellite peaks. The Cu 2p (1/2 and 3/2) peaks at 952.7 and 933 eV could be deconvulated to Cu²⁺ and Cu⁺ individual peaks which also gives the relative proportion of Cu₂O and CuO close to that obtained from the O 1s peak deconvulation. Ni₁₂P₅ and some Ni₅P₄ constituted Ni_xP_y.



Fig. S1: (a) Optical absorption (UV-NIR) spectra spectrum of the bare Cu_2O (red) and the Heterostructures of Cu_2O -CuO (green) and Cu_2O -CuO-Ni_xP_y (blue) thin films deposited on FTO. (b) The Tauc plot and band gap determination of the thin film electrodes. Colours have their defined representations.



Fig. S2: Cross Sectional FESEM images of $Cu_2O-CuO-Ni_xP_y$ showing the representative gradual layers of hetero-interfaces (approximation in the thickness of different layers).

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 Image Mean 	0.000080 nm	 Image Mean 	0.000174 nm	- Image Mean	0.000140 nm
 Image Z Range 	0.229 µm	 Image Z Range 	0.251 µm	- Image Z Range	0.288 µm
 Image Surface Area 	105 µm*	 Image Surface Area 	106 µm²	- Image Surface Area	110 µm ⁻
 Image Projected Surface Area 	100 µm*	 Image Projected Surface Area 	100 µm²	Image Projected Sufface Area	100 µm
 Image Surface Area Difference 	5.14 %	 Image Surface Area Difference 	6.01 %	Image Surface Area Difference	9.03 %
- Image Rq	0.0300 µm	 Image Rq 	0.0236 µm	- Image Kq	0.0209 µm
- Image Ra	0.0238 µm	 Image Ra 	0.0177 µm	Image Ra	0.0208 µm
- Image Rmax	0.229 µm	 Image Rmax 	0.251 µm	- image kmax	0.200 µm
- Kaw Mean	0.352 nm	 Raw Mean 	-0.167 nm	Man	0.00 μm
- Mean	0.552 nm	- Mean	-0.167 nm	7 Papers	0.00 μm
- 2 Kange	0.192 µm	- Z Range	0.153 µm	2 Kange	0.00 µm ²
Designed Surface Area	43.3 µm	 Surface Area 	41.0 µm*	Brojected Surface Area	0.00 µm²
Surface Area Difference	4 07 %	 Projected Surface Area 	38.5 µm*	Surface Area Difference	0.00 %
- Ra	0.0285 um	 Surface Area Difference 	0.000	- Ro	0.00 um
- Ra	0.0226 um	Rq	0.0200 µm	Ra	0.00 um
Rmax	0.185 um	- Ka	0.0103 µm	Rmax	0.00 um
Skewness	0.223 um	Skewpere	0.202 um	- Skewness	0.00 um
- Kurtosis	2.98 µm	Kutosis	2.17 um	- Kurtosis	0.00 um
- Rz	0.00 µm	R*	0.00 um	- Rz	0.00 um
 Rz Count 	0.00	- Bz Count	0.00	- Rz Count	0.00
 Peak Count 	0.00	- Peak Count	0.00	 Peak Count 	0.00
 Valley Count 	0.00	- Valley Count	0.00	- Valley Count	0.00
 Max Peak ht (Rp) 	0.00 µm	- May Peak bt (Rn)	0.00 um	 Max Peak ht (Rp) 	0.00 µm
 Average Max Height (Rpm) 	0.00 µm	- Average Max Height (Rom)	0.00 um	 Average Max Height (Rpm) 	0.00 µm
 Maximum Depth (Rv) 	0.00 µm	Maximum Depth (Ry)	0.00 um	- Maximum Depth (Rv)	0.00 µm
 Average Max Depth (Rvm) 	0.00 µm	- Average Max Depth (Rym)	0.00 um	- Average Max Depth (Rvm)	0.00 µm
 Line Density 	0.00 /µm	- Line Density	0.00 /um	- Line Density	0.00 /µm
Box X Dimension	8.51 µm	- Box X Dimension	7.92 µm	 Box X Dimension 	0.00 µm
 Box Y Dimension 	5.10 µm	Box Y Dimension	4.86 µm	Box Y Dimension	0.00 µm

Fig. S3: Detailed AFM topographic analysis of the electrode surfaces for estimation of roughness factor and grain size study (a) Cu_2O (b) Cu_2O -CuO and (c) Cu_2O -CuO-Ni_xP_y.



Fig. S4: Current–Voltage (I-V) characteristics of a photocathodes: PEC hydrogen evolution activity comparison with and without the Cu₂O-CuO interface to understand the efficiency of photocathode and the role of CuO. All measurements were carried out in pH-7, 0.5 M Na₂SO₄ electrolyte under chopped light irradiation.

Stability of catalyst after PEC study:

The FESEM images before and after 1 hour PEC activity (amperometric I-t study at 0.05 V vs RHE) suggests that after the PEC study morphology changes with more particles on surface causing the smooth electrode surface to be rough although resulting in very slight decrease in photocurrent efficiency.



Fig. S5: Morphology study of electrode: FESEM images of the electrode (a-c) before PEC study and (d-f) after PEC study.



Fig. S6: X-ray diffraction patterns of $Cu_2O-CuO-Ni_xP_y$ before and after PEC study (1 hour chronoamperometric i-t study at 0.05 V vs RHE) to study the stability of the photoelectrode.



Fig S7: Core level X-ray photoelectron spectra for Cu-2p3/2 on the surface of the Cu₂O-CuO-Ni_xP_y electrode before and after PEC stability test. The shaded potion represents the shake of satellite peaks which is more prominent in after PEC sample suggesting greater fraction of CuO on the electrode surface resulting from the photocorrosion.



Fig.S8: Open circuit potential vs time graph of the photocathodes in dark and illuminated conditions obtained by chopping of incident light.

PEC H₂ evolution activity of Cu₂O-CuO-NiO: study of PEC activity with other cocatalyst

Cu₂O-CuO-NiO electrode was fabricated by the method used for other electrodes in this study except in the last step. Pulse plating electrodeposition of Ni(OH)₂ was carried out from a solution of 0.5 M Nickel acetate in 5wt% NMF (without the phosphorous source). The electrodeposition parameters were the same. After deposition the film annealed at 400°C for 30 mins (5°C/min heating rate). The photocurrent study for hydrogen evolution with NiO as cocatalyst suggests that Ni_xP_y is better for HER. This is obvious because of the superior electrochemical HER activity of Ni_xP_y than that of NiO.



Fig. S9: Comparison of PEC activity with NiO as cocatalyst: (a) LSV curve at same conditions as when Ni_xP_y is used as cocatalyst. (b) Transient photocurrent stability test for both the catalysts with Ni_xP_y and NiO as cocatalyst.